	Type	Hits	Search Text	DBs	Time Stamp
1	IS&R	8710	(257/698,752,758,773-776,781,786).CCLS.	USPAT	2008/09/01 08:53
2	IS&R	5935	(257/698,752,758,773-776,781,786).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/01 08:53
3	IS&R	7457	(438/612,614,618,622,629,637,639,640,666,668,672).CCLS.	USPAT	2008/09/01 08:56
4	IS&R	7279	(438/612,614,618,622,629,637,639,640,666,668,672).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/01 08:58
5	BRS	1648	(active transistor gate) and ((bond bonding) near2 (pad)) and ((frame framed) near3 (wire wiring interconnect interconnection layer film))	USPAT	2008/09/01 09:00
6	BRS	1150	(active transistor gate) and ((bond bonding) near2 (pad)) and ((frame framed) near3 (wire wiring interconnect interconnection layer film))	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/01 09:01
7	IS&R	1728	(257/E23.02,E23.152,E23.194).CCLS.	USPAT	2008/09/02 17:32
8	IS&R	15424	((257/698,752,758,773-776,781,786) or (438/612,614,618,622,629,637,639,640,666,668,672)).CCLS.	USPAT	2008/09/02 17:32
9	BRS	752	S60 not S61	USPAT	2008/09/02 17:32
10	IS&R	12380	((257/698,752,758,773-776,781,786) or (438/612,614,618,622,629,637,639,640,666,668,672)).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/02 17:33

	Type	Hits	Search Text	DBs	Time Stamp
11	IS&R	1770	(257/E23.02,E23.152,E23.194).CCLS.	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/02 17:34
12	BRS	1251	S64 not S63	US-PGPUB; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	2008/09/02 17:34
13	BRS	48	((active transistor gate) and ((bond bonding) near2 (pad)) and ((frame framed) near3 (wire wiring interconnect interconnection layer film))).clm.	US-PGPUB	2008/09/02 20:00
14	BRS	0	((active transistor gate) and ((bond bonding) near2 (pad)) and ((frame framed) near3 (wire wiring interconnect interconnection layer film)) and (bus) and (opening via hole)).clm.	USPAT	2008/09/03 08:23
15	BRS	13	((active transistor gate) and ((bond bonding) near2 (pad)) and ((frame framed) near3 (wire wiring interconnect interconnection layer film)) and (opening via hole)).clm.	USPAT	2008/09/03 08:29